Application No.: 10/720,408 Docket No.: 29936/39763

Amendments to the CLAIMS

Please amend claims 1-4 as follows:

1. (Currently Amended) A method for forming a floating gate in a flash memory device, comprising the steps of:

- (a) providing a semiconductor substrate on which a tunnel oxide film and a first polysilicon film are formed;
- (b) <u>sequentially</u> forming a buffer oxide film and a pad nitride film on the first polysilicon film sequentially;
 - (c) forming a trench in the semiconductor substrate;
- (d) depositing a device isolation oxide film to bury <u>fill</u> the trench, and then performing a planarization process using the pad nitride film as a barrier;
- (e) carrying out a strip process to <u>simultaneously</u> remove the pad nitride film and at least 50% of the buffer oxide film, <u>leaving a reduced buffer oxide film on the first polysilicon film at the same time</u>;
- (f) removing the <u>reduced</u> buffer oxide film using a pre-treatment cleaning process; and
- (g) depositing a second polysilicon film on a whole the resulting structure and patterning the second polysilicon film through with a patterning process, whereby forming a to form the floating gate including the first polysilicon film and the second polysilicon film.
- 2. Currently Amended) The method of claim 1, wherein the buffer oxide film is deposited in part (b) with a thickness in the range of 30 Å to 40Å.

Application No.: 10/720,408 Docket No.: 29936/39763

3. (Currently Amended) The method of claim 1, wherein the buffer oxide film is deposited using high temperature oxide (HTO), <u>a</u> tetra ethyl ortho silicate (TEOS), and <u>a</u> DCS-HTO (DiChloroSilane (SiH₂Cl₂)-HTO).

- 4. (Currently Amended) The method of claim 1, after the step part (c) and before part (d), further comprising a step of performing a wall oxidation process for forming a wall oxide film on an inner surface of the trench and on inside walls of the tunnel oxide film, the first polysilicon film, and the buffer oxide film.
- 5. (Original) The method of claim 4, wherein the wall oxidation process is carried out at a temperature in the range of 800°C to 1000°C.